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#### Details

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Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	CANbus, I <sup>2</sup> C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	53
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	1.5K x 8
RAM Size	3K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 24x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s08dz48aclh

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



# Chapter 3 Modes of Operation

# 3.1 Introduction

The operating modes of the MC9S08DZ60 Series are described in this chapter. Entry into each mode, exit from each mode, and functionality while in each of the modes are described.

# 3.2 Features

- Active background mode for code development
- Wait mode CPU shuts down to conserve power; system clocks are running and full regulation is maintained
- Stop modes System clocks are stopped and voltage regulator is in standby
  - Stop3 All internal circuits are powered for fast recovery
  - Stop2 Partial power down of internal circuits; RAM content is retained

# 3.3 Run Mode

This is the normal operating mode for the MC9S08DZ60 Series. This mode is selected when the BKGD/MS pin is high at the rising edge of reset. In this mode, the CPU executes code from internal memory with execution beginning at the address fetched from memory at 0xFFFE–0xFFFF after reset.

# 3.4 Active Background Mode

The active background mode functions are managed through the background debug controller (BDC) in the HCS08 core. The BDC, together with the on-chip debug module (DBG), provide the means for analyzing MCU operation during software development.

Active background mode is entered in any of five ways:

- When the BKGD/MS pin is low at the rising edge of reset
- When a BACKGROUND command is received through the BKGD/MS pin
- When a BGND instruction is executed
- When encountering a BDC breakpoint
- When encountering a DBG breakpoint

After entering active background mode, the CPU is held in a suspended state waiting for serial background commands rather than executing instructions from the user application program.

Chapter 4 Memory

## NOTE

The FCBEF flag will not set after launching the sector erase abort command. If an attempt is made to start a new command write sequence with a sector erase abort operation active, the FACCERR flag in the FSTAT register will be set. A new command write sequence may be started after clearing the ACCERR flag, if set.

## NOTE

The sector erase abort command should be used sparingly since a sector erase operation that is aborted counts as a complete program/erase cycle.

## 4.5.6 Access Errors

An access error occurs whenever the command execution protocol is violated.

Any of the following specific actions will cause the access error flag (FACCERR) in FSTAT to be set. FACCERR must be cleared by writing a 1 to FACCERR in FSTAT before any command can be processed.

- Writing to a Flash address before the internal Flash and EEPROM clock frequency has been set by writing to the FCDIV register.
- Writing to a Flash address while FCBEF is not set. (A new command cannot be started until the command buffer is empty.)
- Writing a second time to a Flash address before launching the previous command. (There is only one write to Flash for every command.)
- Writing a second time to FCMD before launching the previous command. (There is only one write to FCMD for every command.)
- Writing to any Flash control register other than FCMD after writing to a Flash address.
- Writing any command code other than the six allowed codes (0x05, 0x20, 0x25, 0x40, 0x41, or 0x47) to FCMD.
- Writing any Flash control register other than to write to FSTAT (to clear FCBEF and launch the command) after writing the command to FCMD.
- The MCU enters stop mode while a program or erase command is in progress. (The command is aborted.)
- Writing the byte program, burst program, sector erase or sector erase abort command code (0x20, 0x25, 0x40, or 0x47) with a background debug command while the MCU is secured. (The background debug controller can do blank check and mass erase commands only when the MCU is secure.)
- Writing 0 to FCBEF to cancel a partial command.



### Table 5-3. SRS Register Field Descriptions

Field	Description
2 LOC	<ul> <li>Loss of Clock — Reset was caused by a loss of external clock.</li> <li>0 Reset not caused by loss of external clock</li> <li>1 Reset caused by loss of external clock</li> </ul>
1 LVD	<ul> <li>Low-Voltage Detect — If the LVDRE bit is set and the supply drops below the LVD trip voltage, an LVD reset will occur. This bit is also set by POR.</li> <li>0 Reset not caused by LVD trip or POR.</li> <li>1 Reset caused by LVD trip or POR.</li> </ul>

# 5.8.3 System Background Debug Force Reset Register (SBDFR)

This high page register contains a single write-only control bit. A serial background command such as WRITE\_BYTE must be used to write to SBDFR. Attempts to write this register from a user program are ignored. Reads always return 0x00.



<sup>1</sup> BDFR is writable only through serial background debug commands, not from user programs.

## Figure 5-4. System Background Debug Force Reset Register (SBDFR)

### Table 5-4. SBDFR Register Field Descriptions

Field	Description
0 BDFR	<b>Background Debug Force Reset</b> — A serial background command such as WRITE_BYTE can be used to allow an external debug host to force a target system reset. Writing 1 to this bit forces an MCU reset. This bit cannot be written from a user program.



# 5.8.5 System Options Register 2 (SOPT2)

This high page register contains bits to configure MCU specific features on the MC9S08DZ60 Series devices.



## Figure 5-6. System Options Register 2 (SOPT2)

<sup>1</sup> This bit can be written only one time after reset. Additional writes are ignored.

Field	Description
7 COPCLKS	<ul> <li>COP Watchdog Clock Select — This write-once bit selects the clock source of the COP watchdog. See Table 5-6 for details.</li> <li>Internal 1-kHz clock is source to COP.</li> <li>Bus clock is source to COP.</li> </ul>
6 COPW	<ul> <li>COP Window — This write-once bit selects the COP operation mode. When set, the 0x55-0xAA write sequence to the SRS register must occur in the last 25% of the selected period. Any write to the SRS register during the first 75% of the selected period will reset the MCU.</li> <li>0 Normal COP operation.</li> <li>1 Window COP operation.</li> </ul>
4 ADHTS	<ul> <li>ADC Hardware Trigger Select — This bit selects which hardware trigger initiates conversion for the analog to digital converter when the ADC hardware trigger is enabled (ADCTRG is set in ADCSC2 register).</li> <li>0 Real Time Counter (RTC) overflow.</li> <li>1 External Interrupt Request (IRQ) pin.</li> </ul>
2:0 MCSEL	MCLK Divide Select— These bits enable the MCLK output on PTA0 pin and select the divide ratio for the MCLK output according to the formula below when the MCSEL bits are not equal to all zeroes. In case that the MCSEL bits are all zeroes, the MCLK output is disabled. MCLK frequency = Bus Clock frequency ÷ (2 * MCSEL)

### Table 5-7. SOPT2 Register Field Descriptions



### Chapter 7 Central Processor Unit (S08CPUV3)

Source	Operation	dress ode	Object Code	cles	Cyc-by-Cyc	Affect on CCR	
1 Onn		PdA		රි	Details	<b>V</b> 1 1 <b>H</b>	INZC
INC opr8a INCA INCX INC oprx8,X INC ,X INC oprx8,SP	$\begin{array}{llllllllllllllllllllllllllllllllllll$	DIR INH INH IX1 IX SP1	3C dd 4C 5C 6C ff 7C 9E 6C ff	5 1 1 5 4 6	rfwpp p rfwpp rfwp prfwpp	↓11-	- \$ \$ -
JMP opr8a JMP opr16a JMP oprx16,X JMP oprx8,X JMP ,X	Jump PC ← Jump Address	DIR EXT IX2 IX1 IX	BC dd CC hh ll DC ee ff EC ff FC	3 4 4 3 3	2000 2000 2000 2000 2000 2000 2000 200	- 1 1 -	
JSR opr8a JSR opr16a JSR oprx16,X JSR oprx8,X JSR ,X	Jump to Subroutine PC $\leftarrow$ (PC) + $n$ ( $n = 1, 2, \text{ or } 3$ ) Push (PCL); SP $\leftarrow$ (SP) – \$0001 Push (PCH); SP $\leftarrow$ (SP) – \$0001 PC $\leftarrow$ Unconditional Address	DIR EXT IX2 IX1 IX	BD dd CD hh ll DD ee ff ED ff FD	5 6 5 5	ssppp pssppp ssppp ssppp	- 1 1 -	
LDA #opr8i LDA opr8a LDA opr16a LDA oprx16,X LDA oprx8,X LDA ,X LDA oprx16,SP LDA oprx8,SP	Load Accumulator from Memory $A \leftarrow (M)$	IMM DIR EXT IX2 IX1 IX SP2 SP1	A6 ii B6 dd C6 hh ll D6 ee ff E6 ff F6 9E D6 ee ff 9E E6 ff	2 3 4 3 3 5 4	pp rpp prpp rpp rfp pprpp prpp	011-	- ‡ ‡ -
LDHX #opr16i LDHX opr8a LDHX opr16a LDHX ,X LDHX oprx16,X LDHX oprx8,X LDHX oprx8,SP	Load Index Register (H:X) H:X ← (M:M + \$0001)	IMM DIR EXT IX IX2 IX1 SP1	45 jj kk 55 dd 32 hh ll 9E AE 9E BE ee ff 9E CE ff 9E FE ff	3 4 5 5 6 5 5	ppp rrpp prrpp prrfp pprrpp prrpp prrpp	011-	- \$ \$ -
LDX #opr8i LDX opr8a LDX opr16a LDX oprx16,X LDX oprx8,X LDX ,X LDX oprx16,SP LDX oprx8,SP	Load X (Index Register Low) from Memory $X \leftarrow (M)$	IMM DIR EXT IX2 IX1 IX SP2 SP1	AE ii BE dd CE hh ll DE ee ff EE ff FE 9E DE ee ff 9E EE ff	2 3 4 3 3 5 4	pp rpp prpp rpp rfp pprpp prpp	011-	- \$ \$ -
LSL opr8a LSLA LSLX LSL oprx8,X LSL ,X LSL oprx8,SP	Logical Shift Left 	DIR INH INH IX1 IX SP1	38 dd 48 58 68 ff 78 9E 68 ff	5 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↓11-	- ↓ ↓ ↓
LSR opr8a LSRA LSRX LSR oprx8,X LSR ,X LSR oprx8,SP	Logical Shift Right $0 \rightarrow \boxed{1} \\ b7 \\ b0$	DIR INH INH IX1 IX SP1	34 dd 44 54 64 ff 74 9E 64 ff	5 1 1 5 4 6	rfwpp p rfwpp rfwp prfwp	↓11-	- 0 ‡ ‡

Table 7-2. Instruction Set Summary (Sheet 5 of 9)



## 10.1.5 Temperature Sensor

To use the on-chip temperature sensor, the user must perform the following:

- Configure ADC for long sample with a maximum of 1 MHz clock
- Convert the bandgap voltage reference channel (AD27)
  - By converting the digital value of the bandgap voltage reference channel using the value of V<sub>BG</sub> the user can determine V<sub>DD</sub>. For value of bandgap voltage, see Section A.6, "DC Characteristics".
- Convert the temperature sensor channel (AD26)
  - By using the calculated value of  $V_{DD}$ , convert the digital value of AD26 into a voltage,  $V_{TEMP}$

Equation 10-1 provides an approximate transfer function of the temperature sensor.

Temp = 25 - ((
$$V_{TEMP} - V_{TEMP25}$$
)  $\div$  m) Eqn. 10-1

where:

- V<sub>TEMP</sub> is the voltage of the temperature sensor channel at the ambient temperature.
- V<sub>TEMP25</sub> is the voltage of the temperature sensor channel at 25°C.
- m is the hot or cold voltage versus temperature slope in  $V/^{\circ}C$ .

For temperature calculations, use the V<sub>TEMP25</sub> and m values from the ADC Electricals table.

In application code, the user reads the temperature sensor channel, calculates  $V_{TEMP}$  and compares to  $V_{TEMP25}$ . If  $V_{TEMP}$  is greater than  $V_{TEMP25}$  the cold slope value is applied in Equation 10-1. If  $V_{TEMP}$  is less than  $V_{TEMP25}$  the hot slope value is applied in Equation 10-1. To improve accuracy the user should calibrate the bandgap voltage reference and temperature sensor.

Calibrating at 25°C will improve accuracy to  $\pm 4.5$ °C.

Calibration at three points, -40°C, 25°C, and 125°C will improve accuracy to  $\pm 2.5$ °C. Once calibration has been completed, the user will need to calculate the slope for both hot and cold. In application code, the user would then calculate the temperature using Equation 10-1 as detailed above and then determine if the temperature is above or below 25°C. Once determined if the temperature is above or below 25°C, the user can recalculate the temperature using the hot or cold slope value obtained during calibration.



#### Chapter 10 Analog-to-Digital Converter (S08ADC12V1)



## Figure 10-3. Status and Control Register (ADCSC1)

## Table 10-3. ADCSC1 Field Descriptions

Field	Description
7 COCO	Conversion Complete Flag. The COCO flag is a read-only bit set each time a conversion is completed when the compare function is disabled (ACFE = 0). When the compare function is enabled (ACFE = 1), the COCO flag is set upon completion of a conversion only if the compare result is true. This bit is cleared when ADCSC1 is written or when ADCRL is read. 0 Conversion not completed 1 Conversion completed
6 AIEN	Interrupt Enable AIEN enables conversion complete interrupts. When COCO becomes set while AIEN is high, an interrupt is asserted. 0 Conversion complete interrupt disabled 1 Conversion complete interrupt enabled
5 ADCO	<ul> <li>Continuous Conversion Enable. ADCO enables continuous conversions.</li> <li>One conversion following a write to the ADCSC1 when software triggered operation is selected, or one conversion following assertion of ADHWT when hardware triggered operation is selected.</li> <li>Continuous conversions initiated following a write to ADCSC1 when software triggered operation is selected. Continuous conversions are initiated by an ADHWT event when hardware triggered operation is selected.</li> </ul>
4:0 ADCH	Input Channel Select. The ADCH bits form a 5-bit field that selects one of the input channels. The input channels are detailed in Table 10-4. The successive approximation converter subsystem is turned off when the channel select bits are all set. This feature allows for explicit disabling of the ADC and isolation of the input channel from all sources. Terminating continuous conversions this way prevents an additional, single conversion from being performed. It is not necessary to set the channel select bits to all ones to place the ADC in a low-power state when continuous conversions are not enabled because the module automatically enters a low-power state when a conversion completes.

ADCH	Input Select			
00000–01111	AD0–15			
10000–11011	AD16–27			
11100	Reserved			
11101	V <sub>REFH</sub>			
11110	V <sub>REFL</sub>			
11111	Module disabled			

### Table 10-4. Input Channel Select

Field	Description						
7–6 MULT	<b>IIC Multiplier Factor</b> . The MULT bits define the multiplier factor, mul. This factor, along with the SC generates the IIC baud rate. The multiplier factor mul as defined by the MULT bits is provided below 00 mul = 01 01 mul = 02 10 mul = 04 11 Reserved	L divider, v.					
5–0 ICR	<b>IIC Clock Rate</b> . The ICR bits are used to prescale the bus clock for bit rate selection. These bits and the MUI bits determine the IIC baud rate, the SDA hold time, the SCL Start hold time, and the SCL Stop hold time. Table 11-4 provides the SCL divider and hold values for corresponding values of the ICR.						
	The SCL divider multiplied by multiplier factor mul generates IIC baud rate.						
	IIC baud rate = $\frac{\text{bus speed (Hz)}}{\text{mul} \times \text{SCLdivider}}$	Eqn. 11-1					
	SDA hold time is the delay from the falling edge of SCL (IIC clock) to the changing of SDA (IIC data).						
	SDA hold time = bus period (s) $\times$ mul $\times$ SDA hold value	Eqn. 11-2					
	SCL start hold time is the delay from the falling edge of SDA (IIC data) while SCL is high (Start cond falling edge of SCL (IIC clock).	lition) to the					
	SCL Start hold time = bus period (s) $\times$ mul $\times$ SCL Start hold value	Eqn. 11-3					
	SCL stop hold time is the delay from the rising edge of SCL (IIC clock) to the rising edge of SDA SDA (IIC data) while SCL is high (Stop condition).						
	SCL Stop hold time = bus period (s) $\times$ mul $\times$ SCL Stop hold value	Eqn. 11-4					

## Table 11-2. IICF Field Descriptions

For example, if the bus speed is 8 MHz, the table below shows the possible hold time values with different ICR and MULT selections to achieve an IIC baud rate of 100kbps.

мшт	ICP	Hold Times (µs)				
MOLI		SDA	SCL Start	SCL Stop		
0x2	0x00	3.500	3.000	5.500		
0x1	0x07	2.500	4.000	5.250		
0x1	0x0B	2.250	4.000	5.250		
0x0	0x14	2.125	4.250	5.125		
0x0	0x18	1.125	4.750	5.125		

Table 11-3. Hold Time Values for 8 MHz Bus Speed

# 11.3.5 IIC Data I/O Register (IICD)



## Figure 11-7. IIC Data I/O Register (IICD)

### Table 11-7. IICD Field Descriptions

Field	Description
7–0 DATA	<b>Data</b> — In master transmit mode, when data is written to the IICD, a data transfer is initiated. The most significant bit is sent first. In master receive mode, reading this register initiates receiving of the next byte of data.

## NOTE

When transitioning out of master receive mode, the IIC mode should be switched before reading the IICD register to prevent an inadvertent initiation of a master receive data transfer.

In slave mode, the same functions are available after an address match has occurred.

The TX bit in IICC must correctly reflect the desired direction of transfer in master and slave modes for the transmission to begin. For instance, if the IIC is configured for master transmit but a master receive is desired, reading the IICD does not initiate the receive.

Reading the IICD returns the last byte received while the IIC is configured in master receive or slave receive modes. The IICD does not reflect every byte transmitted on the IIC bus, nor can software verify that a byte has been written to the IICD correctly by reading it back.

In master transmit mode, the first byte of data written to IICD following assertion of MST is used for the address transfer and should comprise of the calling address (in bit 7 to bit 1) concatenated with the required  $R/\overline{W}$  bit (in position bit 0).

## 11.3.6 IIC Control Register 2 (IICC2)



Figure 11-8. IIC Control Register (IICC2)

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Field	Description
1 SLPAK	<ul> <li>Sleep Mode Acknowledge — This flag indicates whether the MSCAN module has entered sleep mode (see Section 12.5.5.4, "MSCAN Sleep Mode"). It is used as a handshake flag for the SLPRQ sleep mode request. Sleep mode is active when SLPRQ = 1 and SLPAK = 1. Depending on the setting of WUPE, the MSCAN will clear the flag if it detects activity on the CAN bus while in sleep mode.CPU clearing the SLPRQ bit will also reset the SLPAK bit.</li> <li>0 Running — The MSCAN operates normally</li> <li>1 Sleep mode active — The MSCAN has entered sleep mode</li> </ul>
0 INITAK	Initialization Mode Acknowledge — This flag indicates whether the MSCAN module is in initialization mode (see Section 12.5.5.5, "MSCAN Initialization Mode"). It is used as a handshake flag for the INITRQ initialization mode request. Initialization mode is active when INITRQ = 1 and INITAK = 1. The registers CANCTL1, CANBTR0, CANBTR1, CANIDAC, CANIDAR0–CANIDAR7, and CANIDMR0–CANIDMR7 can be written only by the CPU when the MSCAN is in initialization mode. 0 Running — The MSCAN operates normally 1 Initialization mode active — The MSCAN is in initialization mode

### Table 12-2. CANCTL1 Register Field Descriptions (continued)

# 12.3.3 MSCAN Bus Timing Register 0 (CANBTR0)

The CANBTR0 register configures various CAN bus timing parameters of the MSCAN module.

_	7	6	5	4	3	2	1	0
R W	SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0
Reset:	0	0	0	0	0	0	0	0

Figure 12-6. MSCAN Bus Timing Register 0 (CANBTR0)

## Read: Anytime Write: Anytime in initialization mode (INITRQ = 1 and INITAK = 1)

### Table 12-3. CANBTR0 Register Field Descriptions

Field	Description
7:6 SJW[1:0]	<b>Synchronization Jump Width</b> — The synchronization jump width defines the maximum number of time quanta (Tq) clock cycles a bit can be shortened or lengthened to achieve resynchronization to data transitions on the CAN bus (see Table 12-4).
5:0 BRP[5:0]	<b>Baud Rate Prescaler</b> — These bits determine the time quanta (Tq) clock which is used to build up the bit timing (see Table 12-5).

#### Table 12-4. Synchronization Jump Width

SJW1	SJW0	Synchronization Jump Width
0	0	1 Tq clock cycle
0	1	2 Tq clock cycles
1	0	3 Tq clock cycles
1	1	4 Tq clock cycles



	Data Byte			
DLC3	DLC2	DLC1	DLC0	Count
0	0	0	0	0
0	0	0	1	1
0	0	1	0	2
0	0	1	1	3
0	1	0	0	4
0	1	0	1	5
0	1	1	0	6
0	1	1	1	7
1	0	0	0	8

Table 12-33. Data Length Codes

# 12.4.5 Transmit Buffer Priority Register (TBPR)

This register defines the local priority of the associated message transmit buffer. The local priority is used for the internal prioritization process of the MSCAN and is defined to be highest for the smallest binary number. The MSCAN implements the following internal prioritization mechanisms:

- All transmission buffers with a cleared TXEx flag participate in the prioritization immediately before the SOF (start of frame) is sent.
- The transmission buffer with the lowest local priority field wins the prioritization.

In cases of more than one buffer having the same lowest priority, the message buffer with the lower index number wins.

_	7	6	5	4	3	2	1	0
R W	PRIO7	PRIO6	PRIO5	PRIO4	PRIO3	PRIO2	PRIO1	PRIO0
Reset:	0	0	0	0	0	0	0	0

Figure 12-35. Transmit Buffer Priority Register (TBPR)

Read: Anytime when TXEx flag is set (see Section 12.3.6, "MSCAN Transmitter Flag Register (CANTFLG)") and the corresponding transmit buffer is selected in CANTBSEL (see Section 12.3.10, "MSCAN Transmit Buffer Selection Register (CANTBSEL)").

Write: Anytime when TXEx flag is set (see Section 12.3.6, "MSCAN Transmitter Flag Register (CANTFLG)") and the corresponding transmit buffer is selected in CANTBSEL (see Section 12.3.10, "MSCAN Transmit Buffer Selection Register (CANTBSEL)").

# 12.4.6 Time Stamp Register (TSRH–TSRL)

If the TIME bit is enabled, the MSCAN will write a time stamp to the respective registers in the active transmit or receive buffer as soon as a message has been acknowledged on the CAN bus (see



## 12.5.3.2 Protocol Violation Protection

The MSCAN protects the user from accidentally violating the CAN protocol through programming errors. The protection logic implements the following features:

- The receive and transmit error counters cannot be written or otherwise manipulated.
- All registers which control the configuration of the MSCAN cannot be modified while the MSCAN is on-line. The MSCAN has to be in Initialization Mode. The corresponding INITRQ/INITAK handshake bits in the CANCTL0/CANCTL1 registers (see Section 12.3.1, "MSCAN Control Register 0 (CANCTL0)") serve as a lock to protect the following registers:
  - MSCAN control 1 register (CANCTL1)
  - MSCAN bus timing registers 0 and 1 (CANBTR0, CANBTR1)
  - MSCAN identifier acceptance control register (CANIDAC)
  - MSCAN identifier acceptance registers (CANIDAR0–CANIDAR7)
  - MSCAN identifier mask registers (CANIDMR0–CANIDMR7)
- The TXCAN pin is immediately forced to a recessive state when the MSCAN goes into the power down mode or initialization mode (see Section 12.5.5.6, "MSCAN Power Down Mode," and Section 12.5.5.5, "MSCAN Initialization Mode").
- The MSCAN enable bit (CANE) is writable only once in normal system operation modes, which provides further protection against inadvertently disabling the MSCAN.

## 12.5.3.3 Clock System

Figure 12-42 shows the structure of the MSCAN clock generation circuitry.



Figure 12-42. MSCAN Clocking Scheme

The clock source bit (CLKSRC) in the CANCTL1 register (12.3.2/-226) defines whether the internal CANCLK is connected to the output of a crystal oscillator (oscillator clock) or to the bus clock.

The clock source has to be chosen such that the tight oscillator tolerance requirements (up to 0.4%) of the CAN protocol are met. Additionally, for high CAN bus rates (1 Mbps), a 45% to 55% duty cycle of the clock is required.

Chapter 13 Serial Peripheral Interface (S08SPIV3)



## 13.1.1 Features

Features of the SPI module include:

- Master or slave mode operation
- Full-duplex or single-wire bidirectional option
- Programmable transmit bit rate
- Double-buffered transmit and receive
- Serial clock phase and polarity options
- Slave select output
- Selectable MSB-first or LSB-first shifting

## 13.1.2 Block Diagrams

This section includes block diagrams showing SPI system connections, the internal organization of the SPI module, and the SPI clock dividers that control the master mode bit rate.

## 13.1.2.1 SPI System Block Diagram

Figure 13-2 shows the SPI modules of two MCUs connected in a master-slave arrangement. The master device initiates all SPI data transfers. During a transfer, the master shifts data out (on the MOSI pin) to the slave while simultaneously shifting data in (on the MISO pin) from the slave. The transfer effectively exchanges the data that was in the SPI shift registers of the two SPI systems. The SPSCK signal is a clock output from the master and an input to the slave. The slave device must be selected by a low level on the slave select input ( $\overline{SS}$  pin). In this system, the master device has configured its  $\overline{SS}$  pin as an optional slave select output.



Figure 13-2. SPI System Connections

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### Table 13-7. SPIS Register Field Descriptions

Field	Description
7 SPRF	<ul> <li>SPI Read Buffer Full Flag — SPRF is set at the completion of an SPI transfer to indicate that received data may be read from the SPI data register (SPID). SPRF is cleared by reading SPRF while it is set, then reading the SPI data register.</li> <li>No data available in the receive data buffer</li> <li>Data available in the receive data buffer</li> </ul>
5 SPTEF	SPI Transmit Buffer Empty Flag — This bit is set when there is room in the transmit data buffer. It is cleared by reading SPIS with SPTEF set, followed by writing a data value to the transmit buffer at SPID. SPIS must be read with SPTEF = 1 before writing data to SPID or the SPID write will be ignored. SPTEF generates an SPTEF CPU interrupt request if the SPTIE bit in the SPIC1 is also set. SPTEF is automatically set when a data byte transfers from the transmit buffer into the transmit shift register. For an idle SPI (no data in the transmit buffer or the shift register and no transfer in progress), data written to SPID is transferred to the shifter almost immediately so SPTEF is set within two bus cycles allowing a second 8-bit data value to be queued into the transmit buffer. After completion of the transfer of the value in the shift register, the queued value from the transmit buffer will automatically move to the shifter and SPTEF will be set to indicate there is room for new data in the transmit buffer. If no new data is waiting in the transmit buffer, SPTEF simply remains set and no data moves from the buffer to the shifter.
4 MODF	Master Mode Fault Flag — MODF is set if the SPI is configured as a master and the slave select input goes low, indicating some other SPI device is also configured as a master. The SS pin acts as a mode fault error input only when MSTR = 1, MODFEN = 1, and SSOE = 0; otherwise, MODF will never be set. MODF is cleared by reading MODF while it is 1, then writing to SPI control register 1 (SPIC1). 0 No mode fault error 1 Mode fault error detected

# 13.4.5 SPI Data Register (SPID)

	7	6	5	4	3	2	1	0
R W	Bit 7	6	5	4	3	2	1	Bit 0
Reset	0	0	0	0	0	0	0	0

Figure 13-9. SPI Data Register (SPID)

Reads of this register return the data read from the receive data buffer. Writes to this register write data to the transmit data buffer. When the SPI is configured as a master, writing data to the transmit data buffer initiates an SPI transfer.

Data should not be written to the transmit data buffer unless the SPI transmit buffer empty flag (SPTEF) is set, indicating there is room in the transmit buffer to queue a new transmit byte.

Data may be read from SPID any time after SPRF is set and before another transfer is finished. Failure to read the data out of the receive data buffer before a new transfer ends causes a receive overrun condition and the data from the new transfer is lost.



# 13.5.2 SPI Interrupts

There are three flag bits, two interrupt mask bits, and one interrupt vector associated with the SPI system. The SPI interrupt enable mask (SPIE) enables interrupts from the SPI receiver full flag (SPRF) and mode fault flag (MODF). The SPI transmit interrupt enable mask (SPTIE) enables interrupts from the SPI transmit buffer empty flag (SPTEF). When one of the flag bits is set, and the associated interrupt mask bit is set, a hardware interrupt request is sent to the CPU. If the interrupt mask bits are cleared, software can poll the associated flag bits instead of using interrupts. The SPI interrupt service routine (ISR) should check the flag bits to determine what event caused the interrupt. The service routine should also clear the flag bit(s) before returning from the ISR (usually near the beginning of the ISR).

# 13.5.3 Mode Fault Detection

A mode fault occurs and the mode fault flag (MODF) becomes set when a master SPI device detects an error on the  $\overline{SS}$  pin (provided the  $\overline{SS}$  pin is configured as the mode fault input signal). The  $\overline{SS}$  pin is configured to be the mode fault input signal when MSTR = 1, mode fault enable is set (MODFEN = 1), and slave select output enable is clear (SSOE = 0).

The mode fault detection feature can be used in a system where more than one SPI device might become a master at the same time. The error is detected when a master's  $\overline{SS}$  pin is low, indicating that some other SPI device is trying to address this master as if it were a slave. This could indicate a harmful output driver conflict, so the mode fault logic is designed to disable all SPI output drivers when such an error is detected.

When a mode fault is detected, MODF is set and MSTR is cleared to change the SPI configuration back to slave mode. The output drivers on the SPSCK, MOSI, and MISO (if not bidirectional mode) are disabled.

MODF is cleared by reading it while it is set, then writing to the SPI control register 1 (SPIC1). User software should verify the error condition has been corrected before changing the SPI back to master mode.



Command Mnemonic	Active BDM/ Non-intrusive	Coding Structure	Description
SYNC	Non-intrusive	n/a <sup>1</sup>	Request a timed reference pulse to determine target BDC communication speed
ACK_ENABLE	Non-intrusive	D5/d	Enable acknowledge protocol. Refer to Freescale document order no. HCS08RMv1/D.
ACK_DISABLE	Non-intrusive	D6/d	Disable acknowledge protocol. Refer to Freescale document order no. HCS08RMv1/D.
BACKGROUND	Non-intrusive	90/d	Enter active background mode if enabled (ignore if ENBDM bit equals 0)
READ_STATUS	Non-intrusive	E4/SS	Read BDC status from BDCSCR
WRITE_CONTROL	Non-intrusive	C4/CC	Write BDC controls in BDCSCR
READ_BYTE	Non-intrusive	E0/AAAA/d/RD	Read a byte from target memory
READ_BYTE_WS	Non-intrusive	E1/AAAA/d/SS/RD	Read a byte and report status
READ_LAST	Non-intrusive	E8/SS/RD	Re-read byte from address just read and report status
WRITE_BYTE	Non-intrusive	C0/AAAA/WD/d	Write a byte to target memory
WRITE_BYTE_WS	Non-intrusive	C1/AAAA/WD/d/SS	Write a byte and report status
READ_BKPT	Non-intrusive	E2/RBKP	Read BDCBKPT breakpoint register
WRITE_BKPT	Non-intrusive	C2/WBKP	Write BDCBKPT breakpoint register
GO	Active BDM	08/d	Go to execute the user application program starting at the address currently in the PC
TRACE1	Active BDM	10/d	Trace 1 user instruction at the address in the PC, then return to active background mode
TAGGO	Active BDM	18/d	Same as GO but enable external tagging (HCS08 devices have no external tagging pin)
READ_A	Active BDM	68/d/RD	Read accumulator (A)
READ_CCR	Active BDM	69/d/RD	Read condition code register (CCR)
READ_PC	Active BDM	6B/d/RD16	Read program counter (PC)
READ_HX	Active BDM	6C/d/RD16	Read H and X register pair (H:X)
READ_SP	Active BDM	6F/d/RD16	Read stack pointer (SP)
READ_NEXT	Active BDM	70/d/RD	Increment H:X by one then read memory byte located at H:X
READ_NEXT_WS	Active BDM	71/d/SS/RD	Increment H:X by one then read memory byte located at H:X. Report status and data.
WRITE_A	Active BDM	48/WD/d	Write accumulator (A)
WRITE_CCR	Active BDM	49/WD/d	Write condition code register (CCR)
WRITE_PC	Active BDM	4B/WD16/d	Write program counter (PC)
WRITE_HX	Active BDM	4C/WD16/d	Write H and X register pair (H:X)
WRITE_SP	Active BDM	4F/WD16/d	Write stack pointer (SP)
WRITE_NEXT	Active BDM	50/WD/d	Increment H:X by one, then write memory byte located at H:X
WRITE_NEXT_WS	Active BDM	51/WD/d/SS	Increment H:X by one, then write memory byte located at H:X. Also report status.

Table	17-1.	BDC	Command	Summary

<sup>1</sup> The SYNC command is a special operation that does not have a command code.



#### **Chapter 17 Development Support**

the host must perform ((8 - CNT) - 1) dummy reads of the FIFO to advance it to the first significant entry in the FIFO.

In most trigger modes, the information stored in the FIFO consists of 16-bit change-of-flow addresses. In these cases, read DBGFH then DBGFL to get one coherent word of information out of the FIFO. Reading DBGFL (the low-order byte of the FIFO data port) causes the FIFO to shift so the next word of information is available at the FIFO data port. In the event-only trigger modes (see Section 17.3.5, "Trigger Modes"), 8-bit data information is stored into the FIFO. In these cases, the high-order half of the FIFO (DBGFH) is not used and data is read out of the FIFO by simply reading DBGFL. Each time DBGFL is read, the FIFO is shifted so the next data value is available through the FIFO data port at DBGFL.

In trigger modes where the FIFO is storing change-of-flow addresses, there is a delay between CPU addresses and the input side of the FIFO. Because of this delay, if the trigger event itself is a change-of-flow address or a change-of-flow address appears during the next two bus cycles after a trigger event starts the FIFO, it will not be saved into the FIFO. In the case of an end-trace, if the trigger event is a change-of-flow, it will be saved as the last change-of-flow entry for that debug run.

The FIFO can also be used to generate a profile of executed instruction addresses when the debugger is not armed. When ARM = 0, reading DBGFL causes the address of the most-recently fetched opcode to be saved in the FIFO. To use the profiling feature, a host debugger would read addresses out of the FIFO by reading DBGFH then DBGFL at regular periodic intervals. The first eight values would be discarded because they correspond to the eight DBGFL reads needed to initially fill the FIFO. Additional periodic reads of DBGFH and DBGFL return delayed information about executed instructions so the host debugger can develop a profile of executed instruction addresses.

# 17.3.3 Change-of-Flow Information

To minimize the amount of information stored in the FIFO, only information related to instructions that cause a change to the normal sequential execution of instructions is stored. With knowledge of the source and object code program stored in the target system, an external debugger system can reconstruct the path of execution through many instructions from the change-of-flow information stored in the FIFO.

For conditional branch instructions where the branch is taken (branch condition was true), the source address is stored (the address of the conditional branch opcode). Because BRA and BRN instructions are not conditional, these events do not cause change-of-flow information to be stored in the FIFO.

Indirect JMP and JSR instructions use the current contents of the H:X index register pair to determine the destination address, so the debug system stores the run-time destination address for any indirect JMP or JSR. For interrupts, RTI, or RTS, the destination address is stored in the FIFO as change-of-flow information.

# 17.3.4 Tag vs. Force Breakpoints and Triggers

Tagging is a term that refers to identifying an instruction opcode as it is fetched into the instruction queue, but not taking any other action until and unless that instruction is actually executed by the CPU. This distinction is important because any change-of-flow from a jump, branch, subroutine call, or interrupt causes some instructions that have been fetched into the instruction queue to be thrown away without being executed.



Characteristic	Conditions	Symb	Min	Typ <sup>1</sup>	Max	Unit	Comment
Ref Voltage High		V <sub>REFH</sub>	2.7	V <sub>DDAD</sub>	V <sub>DDAD</sub>	V	Applicable in only 64-pin packages {V <sub>REFH</sub> < V <sub>DDAD</sub> characterized but not production test}
Ref Voltage Low		V <sub>REFL</sub>	V <sub>SSAD</sub>	V <sub>SSAD</sub>	V <sub>SSAD</sub>	V	Not Applicable in 64-pin packages (only 32- and 48-pin packages)
Input Voltage		V <sub>ADIN</sub>	V <sub>REFL</sub>		V <sub>REFH</sub>	V	
Input Capacitance		C <sub>ADIN</sub>	_	4.5	5.5	pF	
Input Resistance		R <sub>ADIN</sub>	_	3	5	kΩ	
Analog Source Resistance	12 bit mode f <sub>ADCK</sub> > 4MHz f <sub>ADCK</sub> < 4MHz	R <sub>AS</sub>	_		2 5	kΩ	External to MCU
	10 bit mode f <sub>ADCK</sub> > 4MHz f <sub>ADCK</sub> < 4MHz				5 10		
	8 bit mode (all valid f <sub>ADCK</sub> )		_	_	10		
ADC	High Speed (ADLPC=0)	f <sub>ADCK</sub>	0.4	_	8.0	MHz	
Clock Freq.	Low Power (ADLPC=1)		0.4	_	4.0		

Table A-9. 1	2-bit ADC	Operating	Conditions	(continued)
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<sup>1</sup> Typical values assume V<sub>DDAD</sub> = 5.0V, Temp = 25°C, f<sub>ADCK</sub>=1.0MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
 <sup>2</sup> DC potential difference.



**Appendix A Electrical Characteristics** 



Figure A-1. ADC Input Impedance Equivalency Diagram

Characteristic	Conditions	С	Symb	Min	Typ <sup>1</sup>	Max	Unit	Comment
Supply Current	ADLPC=1 ADLSMP=1 ADCO=1	Т	I <sub>DD</sub> + I <sub>DDAD</sub>	_	133	_	μΑ	ADC current only
Supply Current	ADLPC=1 ADLSMP=0 ADCO=1	Т	I <sub>DD</sub> + I <sub>DDAD</sub>	—	218	—	μA	ADC current only
Supply Current	ADLPC=0 ADLSMP=1 ADCO=1	Т	I <sub>DD</sub> + I <sub>DDAD</sub>	_	327	_	μA	ADC current only
Supply Current	ADLPC=0 ADLSMP=0 ADCO=1	D	I <sub>DD</sub> + I <sub>DDAD</sub>	_	0.582	1	mA	ADC current only
Supply Current	Stop, Reset, Module Off		I <sub>DD</sub> + I <sub>DDAD</sub>	_	0.011	1	μΑ	ADC current only
ADC	High Speed (ADLPC=0)	Р	f <sub>ADACK</sub>	2	3.3	5	MHz	t <sub>ADACK</sub> =
Clock Source	Low Power (ADLPC=1)			1.25	2	3.3		<sup>1/I</sup> ADACK

Table A-10. 12-bit ADC Characteristics	(V <sub>REFH</sub> = V <sub>DDA</sub>	D, V <sub>REFL</sub> = V <sub>SSAD</sub> )
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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5-1994.

 $\overline{3}$  datums a, b, and d to be determined at datum plane h.

 $\overline{/4.}$  dimensions to be determined at seating plane datum c.

/5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM DIMENSION BY MORE THAN 0.08 MM. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION: 0.07 MM.

<u>6</u> DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 MM PER SIDE. DIMENSIONS ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.

 $\overline{/7.}$  exact shape of each corner is optional.

 $\overline{/8.}$  These dimensions apply to the flat section of the lead between 0.1 MM and 0.25 MM from the lead tip.

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TITLE: LOW PROFILE QUAD FLAT PACK (LQFP) 32 LEAD, 0.8 PITCH (7 X 7 X 1.4)		DOCUMENT NO: 98ASH70029A		RE∨∶D
		CASE NUMBER: 873A-03		19 MAY 2005
		STANDARD: JEDEC MS-026 BBA		